

HSF

NOTES:

Current Rating: 3.0AMP
Contact Resistance: 35mΩ Max
Withstand Voltage: 500V AC/DC
Insulation Resistance: 500MΩ Min
Operation Temperature: -40℃ to +105℃

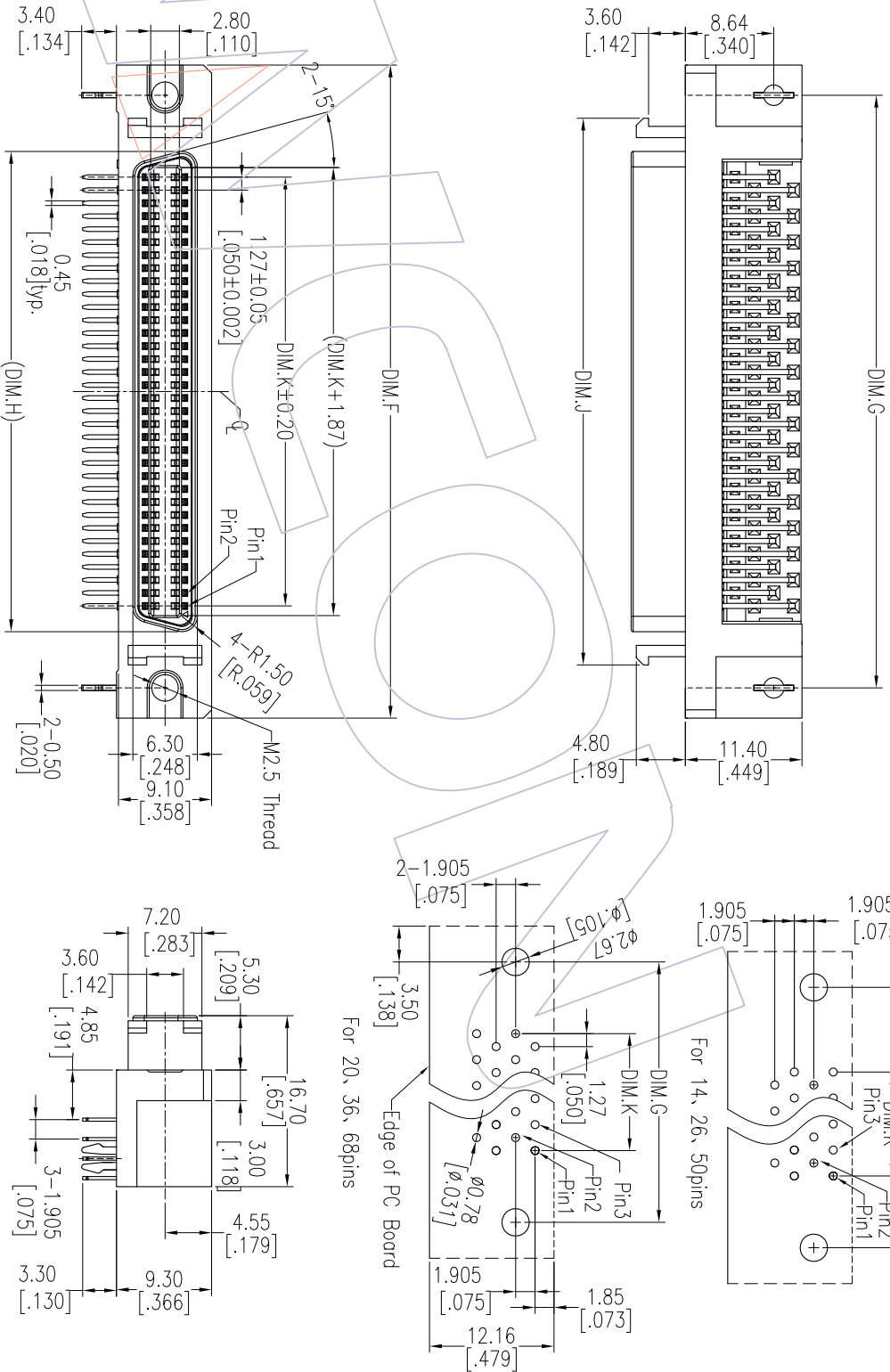
Contact Material: Phosphor Bronze
Contact Plating: Au and Sn over Ni
Shell Material: Zinc Alloy
Shell Plating: Ni 100u"
Fixing Material: Phosphor Bronze
Fixing Plating: Sn over Ni
Housing Material: PBT + 30%G.F (UL94V-0)
Cover Material: PBT + 30%G.F (UL94V-0)

Ordering Information

6321-0XXR D SX MW A01

No. of Pins	Contact Plating	A=Tray
14P 36P	SI=3u"Gold/Tin	
20P 50P	S3=10u"Gold/Tin	
26P 68P	S4=15u"Gold/Tin	
	S5=30u"Gold/Tin	

53.43	41.91	46.83	57.93	63.83	68
42.00	30.48	35.40	46.50	52.40	50
33.11	21.59	26.51	37.61	43.51	36
26.76	15.24	20.16	31.26	37.16	26
22.95	11.43	16.35	27.45	33.35	20
19.14	7.62	12.54	23.64	29.54	14
DIM.J	DIM.K	DIM.H	DIM.G	DIM.F	PIN数



Recommended P.C.B Layout (Top Side)
(PCB BOARD TOLERANCE±0.05)

OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
XX	JYHuang	2013/08/28	UNIT	mm	6321-0XXRDSXMW A01
XXX	CHECK	DATE	SIZE	A4	TITLE:
XXXX	±0.15	DATE	1/2	Customer NO.	1. 27PITCH GEN TYPE
Angle	± 3'	DATE	PROJ.		SCSI FEMALE DIP (鱼叉纵向)
DIM	TOL				

WCON

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REV DATE MODIFICATION DESCRIPTION CHANGE

A1	2013/08/28	Modify	DIM.H
A0	2013/07/03	NEW	